

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A soldering workpiece, comprising:

a soldering workpiece made from aluminum and/or aluminum compounds, wherein the workpiece comprises at a surface a solder plating comprising an aluminum compound,

an oxide and/or hydroxide layer arranged at a surface of the soldering workpiece solder plating, and

a solder layer comprising an aluminum compound, wherein the solder layer is directly applied to the oxide and/or hydroxide layer,

wherein a thickness d of the oxide and/or hydroxide layer is greater than a native thickness of the oxide and/or hydroxide layer of the aluminum and/or aluminum compound formed in ambient air,

wherein the thickness d of the oxide and/or hydroxide layer is greater than 25 nm.

2. (Previously Presented) The soldering workpiece as claimed in claim 1, wherein $25\text{ nm} < d < 1000\text{ nm}$.

3. (Previously Presented) The soldering workpiece as claimed in claim 1, wherein the oxide and/or hydroxide layer includes hydroxide and comprises predominantly of boehmite.

4. (Previously Presented) The soldering workpiece as claimed in claim 1, wherein the oxide and/or hydroxide layer includes inhomogeneities.

5. (Previously Presented) The soldering workpiece as claimed in claim 4, wherein the homogeneities are introduced into the oxide and/or hydroxide layer by chemical and/or thermal and/or mechanical treatment of the soldering workpiece.

6. (Previously Presented) The soldering workpiece as claimed in claim 1, further comprising a halogen-containing lubricant.

7. (Previously Presented) The soldering workpiece as claimed in claim 6, wherein the lubricant includes additives or constituents comprising carboxylic acids, amines, sulfur compounds and/or phosphorus compounds.

8. (Canceled)

9. (Previously Presented) The soldering workpiece as claimed in claim 1, wherein a base material of the soldering workpiece has a magnesium content of greater than 0.2%.

10. (Previously Presented) A soldering process for joining at least two workpieces to one another, comprising:

joining at least two workpieces, wherein at least one workpiece is a workpiece as described in claim 1.

11. (Previously Presented) A soldering process as claimed in claim 10, further comprising at least one machining process that is carried out on at least one workpiece prior to the joining step, wherein a halogen-containing lubricant is applied to the workpiece during the machining processes.

12. (Previously Presented) The soldering process as claimed in claim 11, wherein the lubricant includes additives or constituents comprising carboxylic acids, amines, sulfur compounds and/or phosphorus compounds.

13. (Previously Presented) The soldering process as claimed in claim 10, wherein thermal degreasing and the joining operation are carried out together during a single heating operation.

14. (Previously Presented) The soldering process as claimed in claim 10, wherein a shielding gas is used for heating and/or soldering during the joining step.

15. (Previously Presented) A heat exchanger, comprising a heat exchanger that is at least partially soldered using the process as claimed in claim 10.
16. (Previously Presented) The soldering workpiece as claimed in claim 2, wherein $50 \text{ nm} < d < 500 \text{ nm}$.
17. (Previously Presented) The soldering workpiece as claimed in claim 16, wherein $80 \text{ nm} < d < 250 \text{ nm}$.
18. (Previously Presented) The soldering workpiece as claimed in claim 4, wherein the inhomogeneities comprise notches, pores and/or cracks.
19. (Previously Presented) The soldering workpiece as claimed in claim 9, wherein the magnesium content is greater than 0.2% and less than 2%.
20. (Previously Presented) The soldering process as claimed in claim 11, wherein the at least one machining process comprises a deep-drawing, cutting and/or punching process.
21. (Previously Presented) The soldering process as claimed in claim 14, wherein the shielding gas comprises hydrogen, argon or nitrogen.
22. (Currently Amended) A soldering process for joining at least two workpieces to one another, comprising:
 - providing a soldering workpiece made from aluminum and/or aluminum compounds, wherein the soldering workpiece ~~has~~ comprises a solder plating comprising an aluminum compound at a surface of the soldering workpiece and an oxide and/or hydroxide layer arranged at a surface of the ~~soldering workpiece~~ solder plating,
 - wherein a thickness d of the oxide and/or hydroxide layer is up to 20 nm,
 - increasing the thickness d of the oxide and/or hydroxide layer to a thickness sufficient to provide contact between a soldering compound and the ~~soldering workpiece~~ plating underneath the oxide and/or hydroxide layer during a subsequent soldering process,

introducing inhomogeneities into the oxide and/or hydroxide layer, and
soldering the soldering workpiece to another workpiece.

23. (Previously Presented) The soldering process as claimed in claim 22, wherein the thickness of the oxide and/or hydroxide layer after the increasing step is greater than 25 nm.

24. (Previously Presented) The soldering process as claimed in claim 22, wherein the oxide and/or hydroxide layer separates into fragments that detach from the soldering workpiece during the soldering step.

25. (Previously Presented) The soldering process as claimed in claim 22, wherein the inhomogeneities are introduced by a halogen-containing lubricant.

26. (Currently Amended) A soldering workpiece, comprising:

a soldering workpiece made from aluminum and/or aluminum compounds, wherein the workpiece comprises at a surface a solder plating comprising an aluminum compound, an oxide and/or hydroxide layer located at a surface of the soldering workpiece solder plating with a thickness sufficient to provide contact between a soldering compound and the ~~soldering workpiece~~ plating underneath the oxide and/or hydroxide layer during a subsequent soldering process, and

~~a solder layer comprising an aluminum compound, wherein the solder layer is directly applied to the oxide and/or hydroxide layer,~~

wherein the oxide and/or hydroxide layer includes inhomogeneities introduced into the oxide and/or hydroxide layer,

wherein the thickness of the oxide and/or hydroxide layer is greater than a native thickness of the oxide and/or hydroxide layer,

wherein the thickness of the oxide and/or hydroxide layer is greater than 25 nm.

27. (Previously Presented) The soldering process as claimed in claim 23, wherein $25\text{ nm} < d < 1000\text{ nm}$.

28. (Previously Presented) The soldering process as claimed in claim 22, wherein the inhomogeneities comprise notches, pores and/or cracks.

29. (Previously Presented) The soldering workpiece as claimed in claim 26, wherein a thickness d of the oxide and/or hydroxide layer is $25 \text{ nm} < d < 1000 \text{ nm}$.

30. (Previously Presented) The soldering process as claimed in claim 22, wherein the step of increasing the thickness d of the oxide and/or hydroxide layer comprises heating the soldering workpiece to a temperature of 80°C to 150°C or electrochemically treating the soldering workpiece.